

## LM317L-N $V_{IN}$ 範囲が広い 100mA 可変電圧レギュレータ

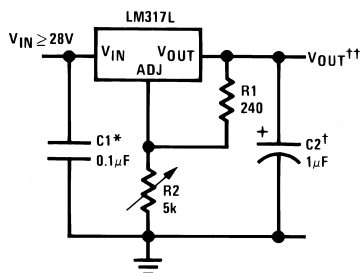
### 1 特長

- 可変出力電圧: 最小1.2V
- 100mAの出力電流
- 最大40Vの $V_{IN}$ に対応
- ライン・レギュレーション: 標準値0.01%/V
- 負荷レギュレーション: 標準値0.1%/A
- 出力コンデンサ不要 (†)
- 温度に対して一定の電流制限
- 多種類の電圧をそろえずに済む
- 標準的な3リード・トランジスタ・パッケージ
- 80dBのリプル除去
- 3ピンTO-92、8ピンSOIC、または6ピンDSBGAパッケージで供給
- 出力の短絡保護
- DSBGAの考慮事項については、AN-1112 (SNVA009)を参照してください。

### 2 アプリケーション

- 車載用LEDライティング
- バッテリー充電器
- スイッチング電源のポスト・レギュレーション
- 定電流レギュレータ
- マイクロプロセッサの電源

回路図



入出力電圧が高いときには出力電流をフルに利用できません。

† オプション—過渡応答性能を向上

\* デバイスがフィルタ・コンデンサから6インチ以上離れて配置される場合は必要

$$†† V_{OUT} = 1.25V \left( 1 + \frac{R_2}{R_1} \right) + I_{ADJ} (R_2)$$

### 3 概要

LM317L-Nは可変正電圧レギュレータであり、-1.2V～37Vの出力範囲で100mAを供給できます。LM317L-Nは簡単に使用でき、2つの外付け抵抗だけで出力電圧を設定できます。ライン・レギュレーションと負荷レギュレーションのいずれも、標準的な固定レギュレータより優れています。LM317L-Nは標準の使いやすいTO-92トランジスタ・パッケージで供給されます。

LM317L-Nは完全な過負荷保護機能を備えています。電流制限、熱過負荷保護、安全領域保護も内蔵されています。デバイスが入力フィルタ・コンデンサから6インチ以上離れて配置されない限り、通常はコンデンサ不要です。6インチ以上離れて配置される場合は入力バイパスが必要です。

LM317L-Nは、フローティング・トポロジを使用して、入出力電圧差のみを監視するため、入出力電圧差の最大値を超過しない限り、数百ボルトの電源でもレギュレート可能です。LM317L-Nは、単純な可変のスイッチング・レギュレータ、またはプログラミング可能な出力レギュレータとして使用でき、さらに調整と出力との間に固定抵抗を接続することで、高精度の電流レギュレータとしても使用できます。

LM317L-Nは標準の3ピンTO-92トランジスタ・パッケージ、8ピンSOICパッケージ、および6ピンDSBGAパッケージで供給されます。LM317L-Nは、-40°C～125°Cでの動作が規定されています。

製品情報<sup>(1)</sup>

型番	パッケージ	本体サイズ(公称)
LM317L-N	TO-92 (3)	4.30mm×4.30mm
	SOIC (8)	3.91mm×4.90mm
	DSBGA (6)	1.68mm×1.019mm

(1) 提供されているすべてのパッケージについては、巻末の注文情報を参照してください。

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## 4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

### Revision K (September 2015) から Revision L に変更

Page

•	Changed TO-92 package view from top to bottom view	3
•	Changed DSBGA package view from bump side down to top view	3
•	Removed duplicate <i>Protection Diodes</i> section and <i>Regulator With Protection Diodes</i> image from the <i>Device Functional Modes</i> section	10

### Revision J (March 2013) から Revision K に変更

Page

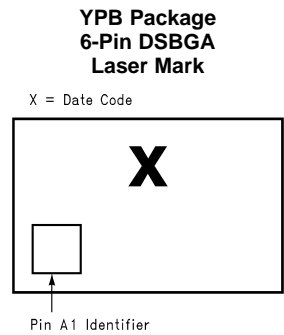
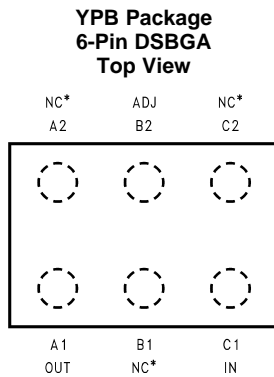
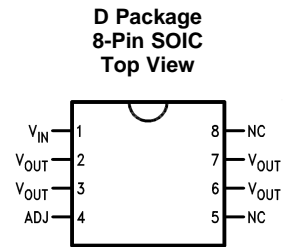
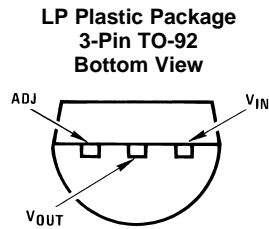
•	「ESD定格」の表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。	1
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### Revision I (March 2013) から Revision J に変更

Page

•	Changed layout of National Semiconductor Data Sheet to TI format	25
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## 5 Pin Configuration and Functions



### Pin Functions

NAME	PIN			I/O	DESCRIPTION
	TO-92	SOIC	DSBGA		
VIN	3	1	C1	I	Supply input pin
VOUT	2	2, 3, 6, 7	A1	O	Voltage output pin
ADJ	1	4	B2	I	Output voltage adjustment pin. Connect to a resistor divider to set $V_O$ .
NC	—	5, 8	B1, A2, C2	—	No connection

## 6 Specifications

### 6.1 Absolute Maximum Rating <sup>(1)(2)</sup>

	MIN	MAX	UNIT
Power dissipation	Internally Limited		
Input-output voltage differential		40	V
Operating junction temperature	-40	125	°C
Lead temperature (soldering, 4 seconds)		260	°C
Storage temperature, $T_{stg}$	-55	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) If Military/Aerospace specified devices are required, contact the Texas Instruments Sales Office/Distributors for availability and specifications.

### 6.2 ESD Ratings

	VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as ±2000 V may actually have higher performance.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Operating temperature	-40	125	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	LM317L-N				UNIT
	TO-92		SOIC	DSBGA	
	3 PINS		8 PINS	6 PINS	
	0.4-in Leads	0.125-in Leads			
$R_{\theta JA}$ Junction-to-ambient thermal resistance	180	160	165	290	°C/W
$R_{\theta JC(top)}$ Junction-to-case (top) thermal resistance	—	80.6	—	—	°C/W
$R_{\theta JB}$ Junction-to-board thermal resistance	—	—	—	—	°C/W
$\psi_{JT}$ Junction-to-top characterization parameter	—	24.7	—	—	°C/W
$\psi_{JB}$ Junction-to-board characterization parameter	—	135.8	—	—	°C/W
$R_{\theta JC(bot)}$ Junction-to-case (bottom) thermal resistance	—	—	—	—	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics <sup>(1)</sup>

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Line regulation	$T_J = 25^\circ\text{C}$ , $3\text{ V} \leq (V_{IN} - V_{OUT}) \leq 40\text{ V}$ , $I_L \leq 20\text{ mA}$ <sup>(2)</sup>		0.01	0.04	%/V
Load regulation	$T_J = 25^\circ\text{C}$ , $5\text{ mA} \leq I_{OUT} \leq I_{MAX}$ <sup>(2)</sup>		0.1%	0.5%	
Thermal regulation	$T_J = 25^\circ\text{C}$ , 10-ms Pulse		0.04	0.2	%/W
Adjustment pin current			50	100	$\mu\text{A}$
Adjustment pin current change	$5\text{ mA} \leq I_L \leq 100\text{ mA}$ $3\text{ V} \leq (V_{IN} - V_{OUT}) \leq 40\text{ V}$ , $P \leq 625\text{ mW}$		0.2	5	$\mu\text{A}$
Reference voltage	$3\text{ V} \leq (V_{IN} - V_{OUT}) \leq 40\text{ V}$ <sup>(3)</sup> $5\text{ mA} \leq I_{OUT} \leq 100\text{ mA}$ , $P \leq 625\text{ mW}$	1.2	1.25	1.3	V
Line regulation	$3\text{ V} \leq (V_{IN} - V_{OUT}) \leq 40\text{ V}$ , $I_L \leq 20\text{ mA}$ <sup>(2)</sup>		0.02	0.07	%/V
Load regulation	$5\text{ mA} \leq I_{OUT} \leq 100\text{ mA}$ <sup>(2)</sup>		0.3%	1.5%	
Temperature stability	$T_{MIN} \leq T_J \leq T_{MAX}$		0.65%		
Minimum load current	$(V_{IN} - V_{OUT}) \leq 40\text{ V}$		3.5	5	mA
	$3\text{ V} \leq (V_{IN} - V_{OUT}) \leq 15\text{ V}$		1.5	2.5	
Current limit	$3\text{ V} \leq (V_{IN} - V_{OUT}) \leq 13\text{ V}$	100	200	300	mA
	$(V_{IN} - V_{OUT}) = 40\text{ V}$	25	50	150	
RMS output noise, % of $V_{OUT}$	$T_J = 25^\circ\text{C}$ , $10\text{ Hz} \leq f \leq 10\text{ kHz}$		0.003%		
Ripple rejection ratio	$V_{OUT} = 10\text{ V}$ , $f = 120\text{ Hz}$ , $C_{ADJ} = 0$		65		dB
	$C_{ADJ} = 10\text{ }\mu\text{F}$	66	80		
Long-term stability	$T_J = 125^\circ\text{C}$ , 1000 Hours		0.3%	1%	

- (1) Unless otherwise noted, these specifications apply:  $-25^\circ\text{C} \leq T_J \leq 125^\circ\text{C}$  for the LM317L-N;  $V_{IN} - V_{OUT} = 5\text{ V}$  and  $I_{OUT} = 40\text{ mA}$ . Although power dissipation is internally limited, these specifications are applicable for power dissipations up to 625 mW.  $I_{MAX}$  is 100 mA.
- (2) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.
- (3) Thermal resistance of the TO-92 package is  $180^\circ\text{C/W}$  junction to ambient with 0.4-inch leads from a PCB and  $160^\circ\text{C/W}$  junction to ambient with 0.125-inch lead length to PCB.

LM317L-N

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6.6 Typical Characteristics

(Output capacitor = 0  $\mu$ F unless otherwise noted.)

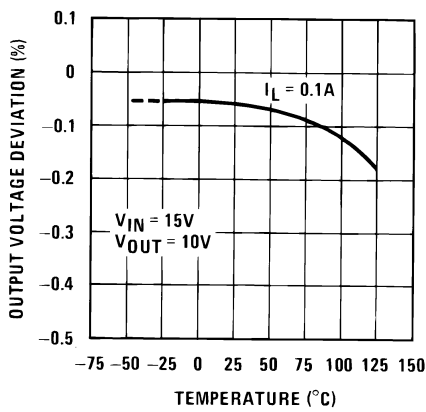


Figure 1. Load Regulation

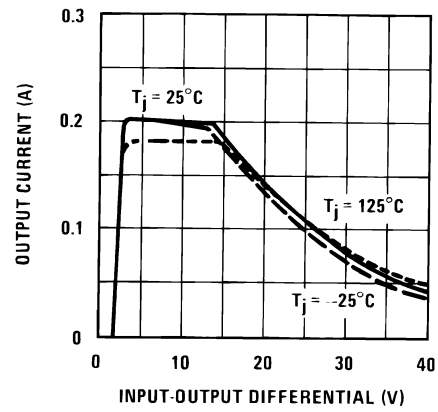


Figure 2. Current Limit

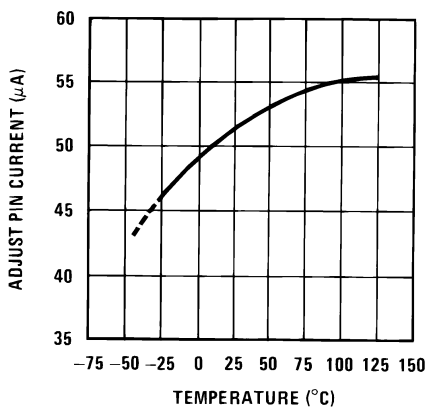


Figure 3. Adjustment Current

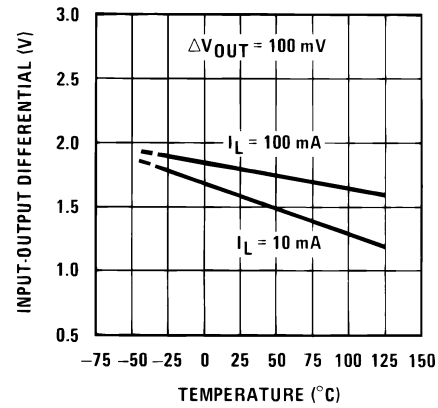


Figure 4. Dropout Voltage

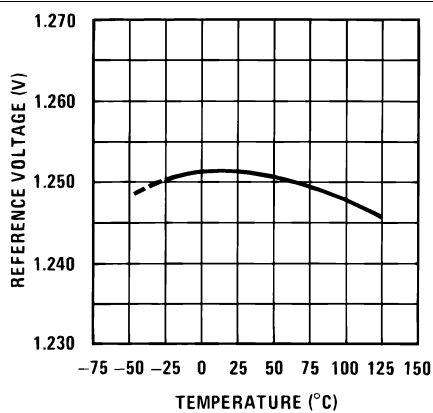


Figure 5. Reference Voltage Temperature Stability

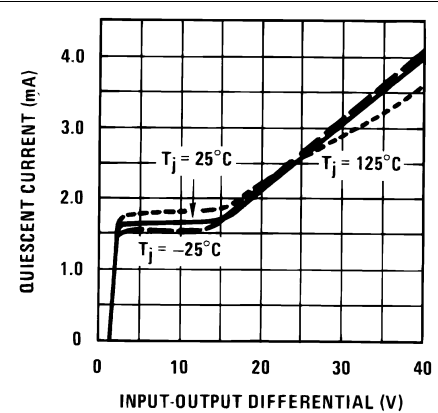


Figure 6. Minimum Operating Current

Typical Characteristics (continued)

(Output capacitor = 0  $\mu$ F unless otherwise noted.)

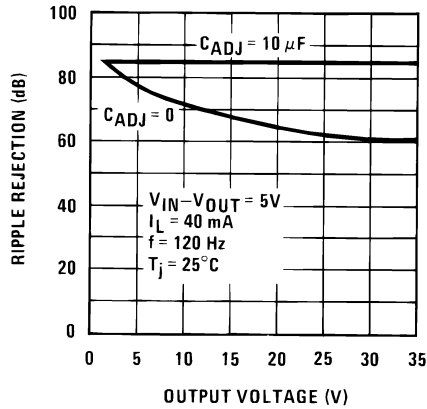


Figure 7. Ripple Rejection

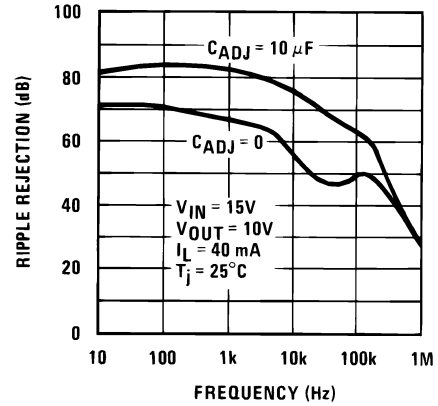


Figure 8. Ripple Rejection

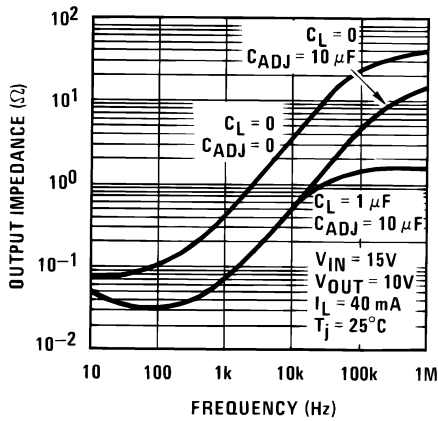


Figure 9. Output Impedance

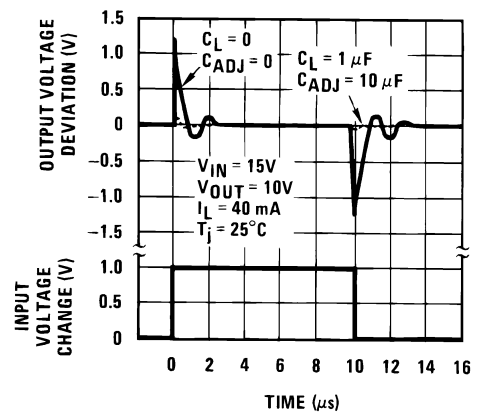


Figure 10. Line Transient Response

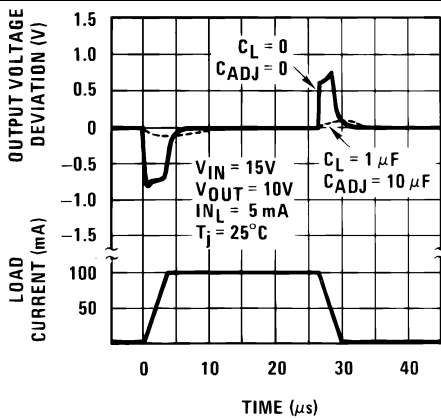


Figure 11. Load Transient Response

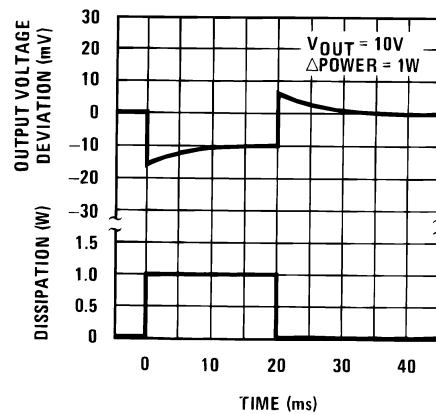


Figure 12. Thermal Regulation

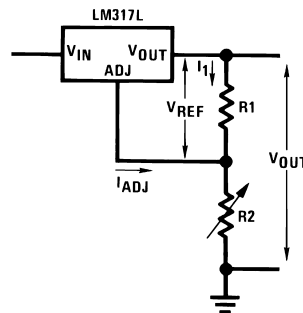
## 7 Detailed Description

### 7.1 Overview

In operation, the LM317L-N develops a nominal 1.25-V reference voltage,  $V_{REF}$ , between the output and adjustment terminal. The reference voltage is impressed across program resistor  $R1$  and, because the voltage is constant, a constant current  $I_1$  then flows through the output set resistor  $R2$ , giving an output voltage of:

$$V_{OUT} = V_{REF} \left( 1 + \frac{R2}{R1} \right) + I_{ADJ}(R2) \quad (1)$$

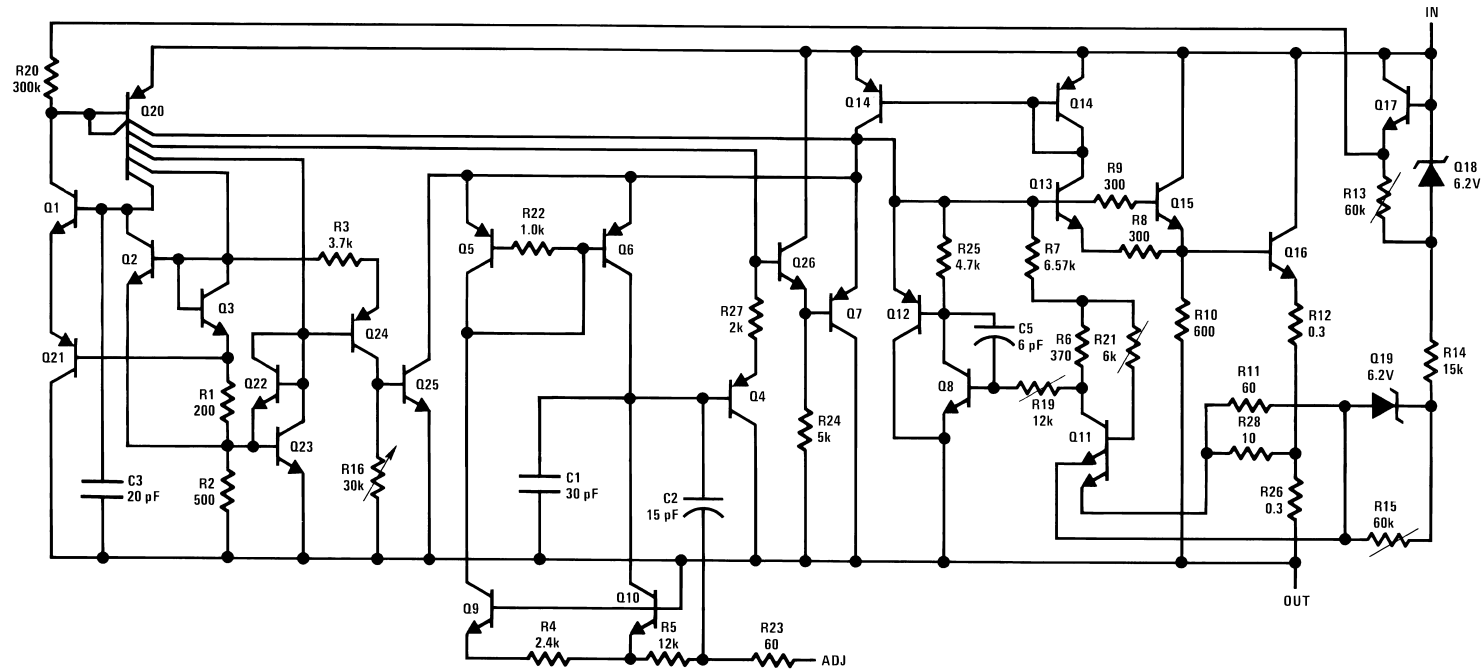
Because the 100- $\mu$ A current from the adjustment terminal represents an error term, the LM317L-N was designed to minimize  $I_{ADJ}$  and make it very constant with line and load changes. To do this, all quiescent operating current is returned to the output establishing a minimum load current requirement. If there is insufficient load on the output, the output will rise.



**Figure 13. Typical Application Circuit for Adjustable Regulator**



## 7.2 Functional Block Diagram



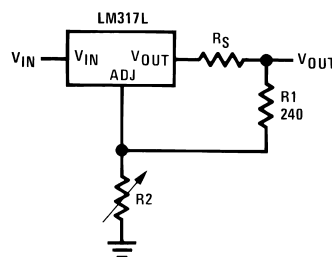
## 7.3 Feature Description

### 7.3.1 Load Regulation

The LM317L-N is capable of providing extremely good load regulation but a few precautions are needed to obtain maximum performance. The current set resistor connected between the adjustment terminal and the output terminal (usually 240  $\Omega$ ) must be tied directly to the output of the regulator rather than near the load. This eliminates line drops from appearing effectively in series with the reference and degrading regulation. For example, a 15-V regulator with 0.05- $\Omega$  resistance between the regulator and load will have a load regulation due to line resistance of 0.05  $\Omega \times I_L$ . If the set resistor is connected near the load the effective line resistance will be 0.05  $\Omega (1 + R_2/R_1)$  or in this case, 11.5 times worse.

Figure 14 shows the effect of resistance between the regulator and 240- $\Omega$  set resistor.

With the TO-92 package, it is easy to minimize the resistance from the case to the set resistor, by using two separate leads to the output pin. The ground of R2 can be returned near the ground of the load to provide remote ground-sensing and improve load regulation.



**Figure 14. Regulator With Line Resistance in Output Lead**

## 7.4 Device Functional Modes

### 7.4.1 External Capacitors

An input bypass capacitor is recommended in case the regulator is more than 6 inches away from the usual large filter capacitor. A 0.1- $\mu\text{F}$  disc or 1- $\mu\text{F}$  solid tantalum on the input is suitable input bypassing for almost all applications. The device is more sensitive to the absence of input bypassing when adjustment or output capacitors are used, but the above values will eliminate the possibility of problems.

The adjustment terminal can be bypassed to ground on the LM317L-N to improve ripple rejection and noise. This bypass capacitor prevents ripple and noise from being amplified as the output voltage is increased. With a 10- $\mu\text{F}$  bypass capacitor 80-dB ripple rejection is obtainable at any output level. Increases over 10- $\mu\text{F}$  do not appreciably improve the ripple rejection at frequencies above 120 Hz. If the bypass capacitor is used, it is sometimes necessary to include protection diodes to prevent the capacitor from discharging through internal low current paths and damaging the device.

In general, the best type of capacitors to use is solid tantalum. *Solid tantalum capacitors have low impedance even at high frequencies.* Depending upon capacitor construction, it takes about 25  $\mu\text{F}$  in aluminum electrolytic to equal 1- $\mu\text{F}$  solid tantalum at high frequencies. Ceramic capacitors are also good at high frequencies; but some types have a large decrease in capacitance at frequencies around 0.5 MHz. For this reason, a 0.01- $\mu\text{F}$  disc may seem to work better than a 0.1- $\mu\text{F}$  disc as a bypass.

Although the LM317L-N is stable with no output capacitors, like any feedback circuit, certain values of external capacitance can cause excessive ringing. This occurs with values between 500 pF and 5000 pF. A 1- $\mu\text{F}$  solid tantalum (or 25- $\mu\text{F}$  aluminum electrolytic) on the output swamps this effect and insures stability.

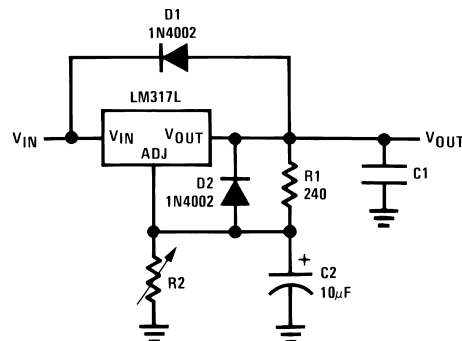
### 7.4.2 Protection Diodes

When external capacitors are used with *any* IC regulator it is sometimes necessary to add protection diodes to prevent the capacitors from discharging through low current points into the regulator. Most 10- $\mu\text{F}$  capacitors have low enough internal series resistance to deliver 20-A spikes when shorted. Although the surge is short, there is enough energy to damage parts of the IC.

## Device Functional Modes (continued)

When an output capacitor is connected to a regulator and the input is shorted, the output capacitor will discharge into the output of the regulator. The discharge current depends on the value of the capacitor, the output voltage of the regulator, and the rate of decrease of  $V_{IN}$ . In the LM317L-N, this discharge path is through a large junction that is able to sustain a 2-A surge with no problem. This is not true of other types of positive regulators. For output capacitors of 25  $\mu\text{F}$  or less, the ballast resistors and output structure of the LM317L-N limit the peak current to a low enough level so that there is no need to use a protection diode.

The bypass capacitor on the adjustment terminal can discharge through a low current junction. Discharge occurs when *either* the input or output is shorted. Internal to the LM317L-N is a 50- $\Omega$  resistor which limits the peak discharge current. No protection is needed for output voltages of 25 V or less and 10- $\mu\text{F}$  capacitance. Figure 15 shows an LM317L-N with protection diodes included for use with outputs greater than 25 V and high values of output capacitance.



$$V_{OUT} = V_{REF} \left( 1 + \frac{R2}{R1} \right) + I_{ADJ}(R2)$$

D1 protects against C1

D2 protects against C2

Figure 15. Regulator With Protection Diodes

### 7.4.3 DSBGA Light Sensitivity

Exposing the LM317L-N DSBGA package to bright sunlight may cause the  $V_{REF}$  to drop. In a normal office environment of fluorescent lighting the output is not affected. The LM317 DSBGA does not sustain permanent damage from light exposure. Removing the light source causes  $V_{REF}$  of the LM317L-N to recover to the proper value.

## 8 Application and Implementation

### NOTE

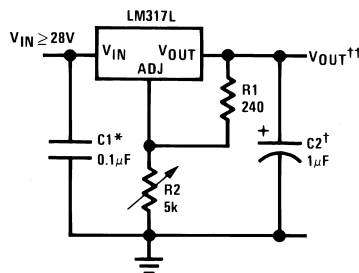
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The LM317L-N is a versatile, high-performance, linear regulator with 1% output-voltage accuracy. An output capacitor can be added to further improve transient response, and the ADJ pin can be bypassed to achieve very high ripple-rejection ratios. Its functionality can be used in many different applications that require high performance regulation, such as battery chargers, constant-current regulators, and microprocessor supplies.

### 8.2 Typical Applications

#### 8.2.1 1.25-V to 25-V Adjustable Regulator



Full output current not available at high input-output voltages

†Optional—improves transient response

\*Needed if device is more than 6 inches from filter capacitors

$$\dagger\dagger V_{OUT} = 1.25V \left( 1 + \frac{R2}{R1} \right) + I_{ADJ} (R2)$$

**Figure 16. 1.25-V to 25-V Adjustable Regulator**

#### 8.2.1.1 Design Requirements

The device component count is very minimal, employing two resistors as part of a voltage-divider circuit and an output capacitor for load regulation. An input capacitor is needed if the device is more than 6 inches from filter capacitors. An optional bypass capacitor across R2 can also be used to improve PSRR.

#### 8.2.1.2 Detailed Design Procedure

The output voltage is set based on the selection of the two resistors, R1 and R2, as shown in [Figure 16](#). For details on capacitor selection, see [External Capacitors](#).

## Typical Applications (continued)

### 8.2.1.3 Application Curve

As shown in Figure 17,  $V_{OUT}$  rises with  $V_{IN}$  minus some dropout voltage. This dropout voltage during start-up will vary with  $R_{OUT}$ .

$$V_{OUT} = 5\text{ V}$$

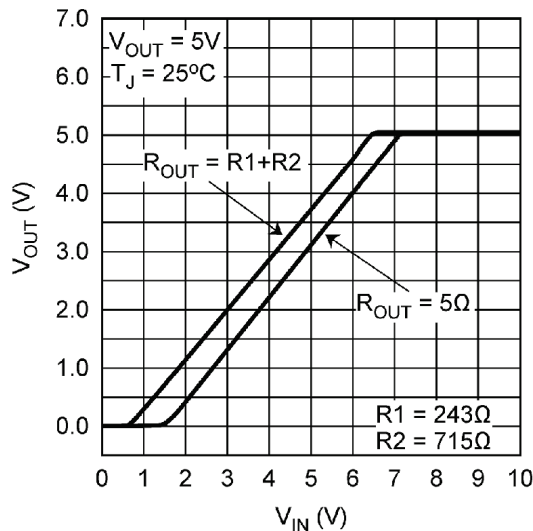
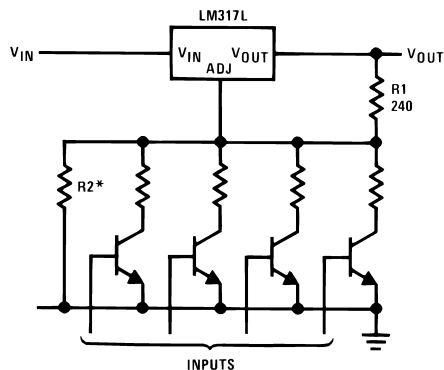


Figure 17.  $V_{OUT}$  vs  $V_{IN}$

### 8.2.2 Digitally-Selected Outputs

Figure 18 demonstrates a digitally-selectable output voltage. In its default state, all transistors are off and the output voltage is set based on  $R1$  and  $R2$ . By driving certain transistors, the associated resistor is connected in parallel to  $R2$ , modifying the output voltage of the regulator.



\*Sets maximum  $V_{OUT}$

Figure 18. Digitally-Selected Outputs

## Typical Applications (continued)

### 8.2.3 High Gain Amplifier

This application uses the LM395 Power Transistor to amplify the input voltage. The LM317L connected to R2 produces a constant current of  $1.2V/R2$  through the BJT. By altering the base current entering the LM395, the effective resistance can be changed resulting in an appropriate voltage fluctuation at the output.

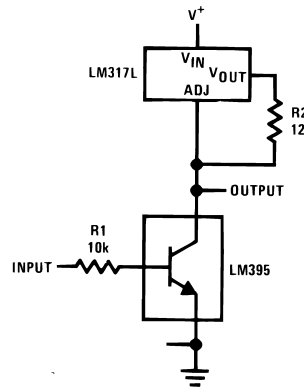
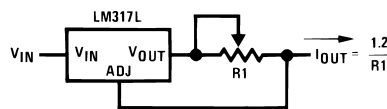


Figure 19. High Gain Amplifier

### 8.2.4 Adjustable Current Limiter

This application will limit the output current to the  $I_{OUT}$  in the diagram. The current limit is determined by adjusting the resistance between the  $V_{OUT}$  and  $V_{ADJ}$  pins. The 1.2-V reference voltage across R1 generates the maximum current.



$$12 \leq R1 \leq 240$$

Figure 20. Adjustable Current Limiter

### 8.2.5 Precision Current Limiter

This application will limit the output current to the  $I_{OUT}$  in the diagram. An initial reference current is generated based on the resistance between the  $V_{OUT}$  and  $V_{ADJ}$  pins. In the case of Figure 21, 1.25 V across 1 k $\Omega$  plus half of the 500- $\Omega$  resistor results in 1 mA of current, producing 1.5 V total across the two resistors in series. This voltage also appears across R1, making the maximum current the sum of the branch currents.

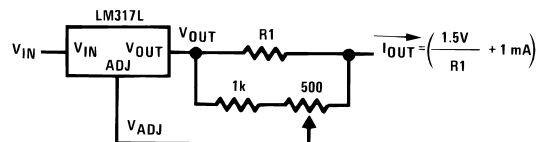


Figure 21. Precision Current Limiter

## Typical Applications (continued)

### 8.2.6 Slow Turnon 15-V Regulator

An application of LM317L-N includes a PNP transistor with a capacitor to implement slow turnon functionality (see Figure 22). As  $V_{IN}$  rises, the PNP sinks current from the ADJ rail. The output voltage at start-up is the addition of the 1.25-V reference plus the drop across the base to emitter. While this is happening, the capacitor begins to charge and eventually opens the PNP. At this point, the device functions normally, regulating the output at 15 V. A diode is placed between C1 and  $V_{OUT}$  to provide a path for the capacitor to discharge. Such controlled turnon is useful for limiting the in-rush current.

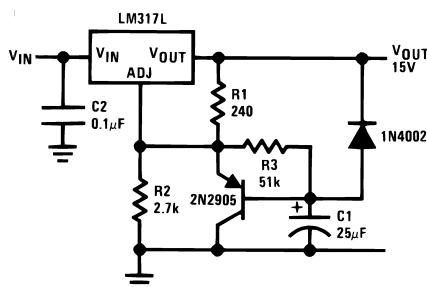
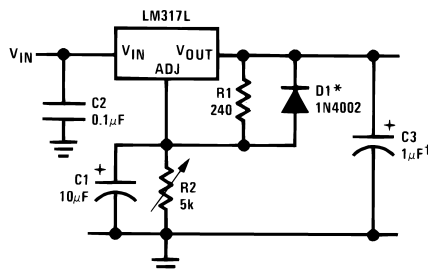


Figure 22. Slow Turnon 15-V Regulator

### 8.2.7 Adjustable Regulator With Improved Ripple Rejection

To improve ripple rejection, a capacitor is used to bypass the ADJ pin to GND (see Figure 23). This is used to smooth output ripple by cleaning the feedback path and stopping unnecessary noise from being fed back into the device, propagating the noise.



†Solid tantalum

\*Discharges C1 if output is shorted to ground

Figure 23. Adjustable Regulator With Improved Ripple Rejection

### 8.2.8 High Stability 10-V Regulator

This application will regulate to an output voltage of 10 V and will remain stable even with input voltage transients. The LM329 is a precision Zener reference diode that helps maintain stability.

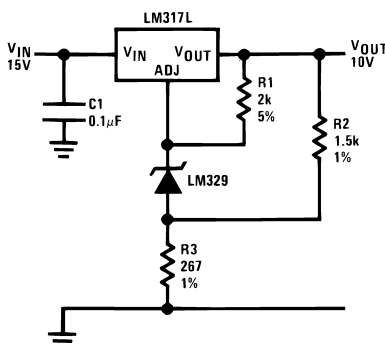
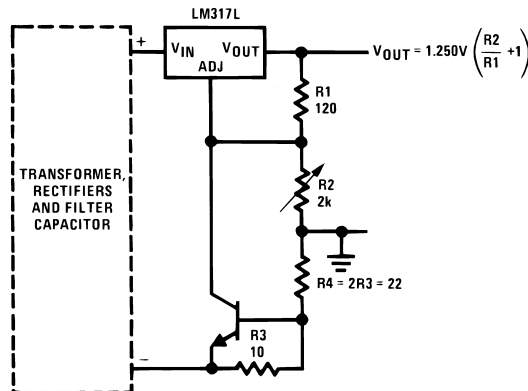


Figure 24. High Stability 10-V Regulator

Typical Applications (continued)

8.2.9 Adjustable Regulator With Current Limiter

This application regulates to an output voltage set by the ratio of R2 and R1 and limits the output current using R3 as shown in Figure 25.

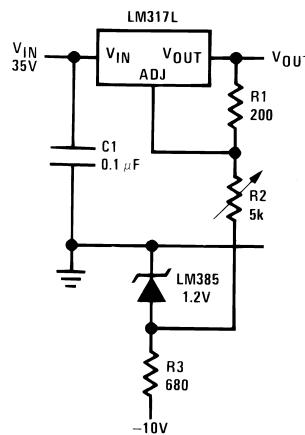


Short circuit current is approximately 600 mV/R3, or 60 mA (compared to LM317L-NZ's 200-mA current limit). At 25-mA output only 3/4 V of drop occurs in R3 and R4.

Figure 25. Adjustable Regulator With Current Limiter

8.2.10 0-V to 30-V Regulator

This application regulates the output voltage from 0 V to 30 V using the resistor divider at the output. The adjustment pin reference voltage is 1.25 V so select the resistor divider that provides the needed output voltage.



Full output current not available at high input-output voltages

Figure 26. 0-V to 30-V Regulator



## Typical Applications (continued)

### 8.2.11 Regulator With 15-mA Short-Circuit Current

This application regulates to a 10-V output with a 15-mA short-circuit current. The output voltage is set by the resistor divider at the output and the PNP is required to set the short-circuit current.

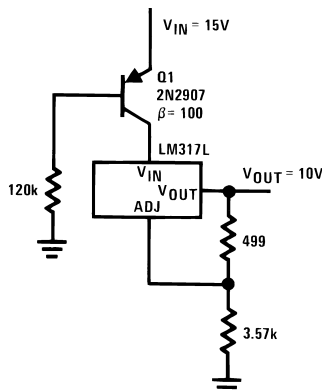


Figure 27. Regulator With 15-mA Short-Circuit Current

### 8.2.12 Power Follower

This application provides an output voltage that follows the input voltage while providing a current gain. The LM395 is a power transistor that operates as an emitter follower and provides a short-circuit current limit while the LM317 acts as a constant-current load.

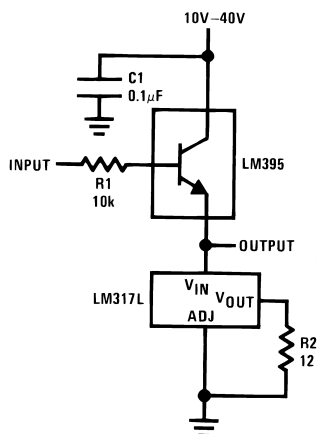
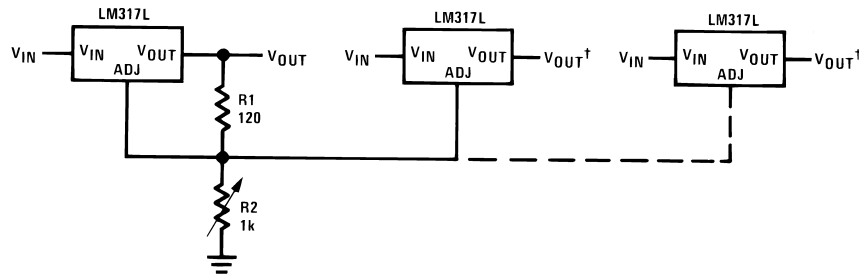


Figure 28. Power Follower

**Typical Applications (continued)**

**8.2.13 Adjusting Multiple On-Card Regulators With Single Control**

Figure 29 shows how multiple LM317L-N regulators can be controlled by setting one resistor. Because each device maintains the reference voltage of about 1.25 V between its  $V_{OUT}$  and ADJ pins, we can connect each ADJ rail to a single resistor, setting the same output voltage across all devices. This allows for independent outputs, each responding to its corresponding input only. Designers must also consider that by the nature of the circuit, changes to R1 and R2 will affect all regulators.

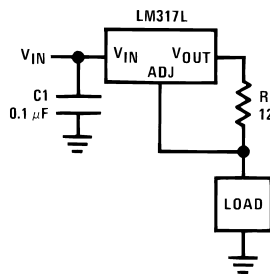


\*All outputs within  $\pm 100$  mV  
 †Minimum load –5 mA

**Figure 29. Adjusting Multiple On-Card Regulators With Single Control\***

**8.2.14 100-mA Current Regulator**

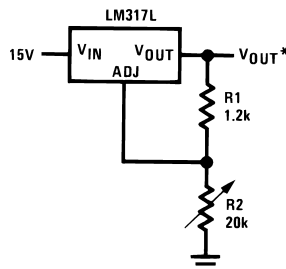
This application regulates the output current to maximum of 100 mA as shown in Figure 30.



**Figure 30. 100-mA Current Regulator**

**8.2.15 1.2-V to 12-V Regulator With Minimum Program Current**

This application regulates the output voltage between 1.2 V and 12 V depending on the resistor divider at the output while allowing minimum programmable load current down to 2 mA as shown in Figure 31.



\*Minimum load current  $\approx 2$  mA

**Figure 31. 1.2-V to 12-V Regulator With Minimum Program Current**

## Typical Applications (continued)

### 8.2.16 50-mA Constant Current Battery Charger for Nickel-Cadmium Batteries

This application provides a 50-mA constant current at the output which can be used as a constant current battery charger for Nickel-Cadmium batteries. The resistor at the output sets the output current value.

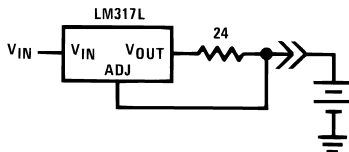
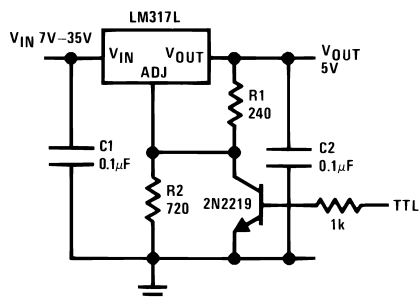


Figure 32. 50-mA Constant Current Battery Charger for Nickel-Cadmium Batteries

### 8.2.17 5-V Logic Regulator With Electronic Shutdown

Figure 33 shows a variation of the 5-V output regulator application uses the LM317L-N, along with an NPN transistor, to provide shutdown control. The NPN will either block or sink the current from the ADJ pin by responding to the TTL pin logic. When TTL is pulled high, the NPN is on and pulls the ADJ pin to GND, and the LM317L-N outputs about 1.25 V. When TTL is pulled low, the NPN is off and the regulator outputs according to the programmed adjustable voltage.

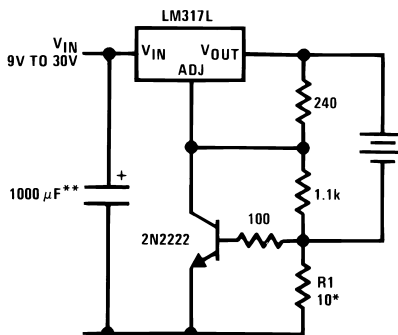


\*Minimum output  $\approx 1.2$  V

Figure 33. 5-V Logic Regulator With Electronic Shutdown\*

### 8.2.18 Current-Limited 6-V Charger

The current in a battery charger application is limited by switching between constant-current and constant-voltage states (see Figure 34). When the battery pulls low current, the drop across the 1- $\Omega$  resistor is not substantial and the NPN remains off. A constant voltage is seen across the battery, as regulated by the resistor divider. When current through the battery rises past peak current, the 1  $\Omega$  provides enough voltage to turn the transistor on, pulling ADJ close to ground. This results in limiting the maximum current to the battery.



\*Sets peak current,  $I_{PEAK} = 0.6 \text{ V}/R1$

\*\*1000  $\mu\text{F}$  is recommended to filter out any input transients.

Figure 34. Current Limited 6-V Charger

Typical Applications (continued)

8.2.19 Short Circuit-Protected 80-V Supply

This application provides a 80-V output voltage from 0 mA to 20 mA as shown in Figure 35. The Triad provides an AC to DC conversion and the short-circuit protection is provided by the fuse. The output voltage can be adjusted by adjusting the resistor divider at the output.

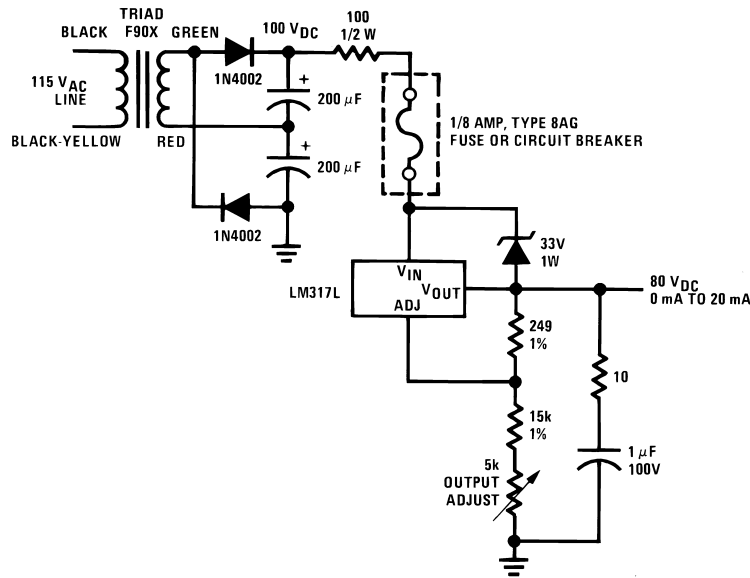
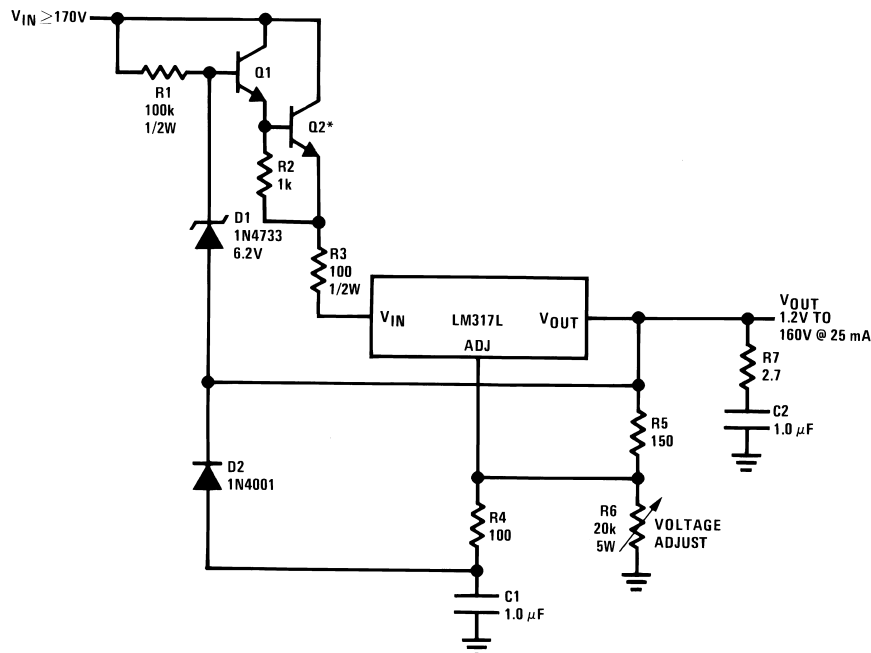


Figure 35. Short Circuit-Protected 80-V Supply

Typical Applications (continued)

8.2.20 Basic High-Voltage Regulator

This application regulates the output voltage from 1.2 V to 160 V at 25 mA as shown in Figure 36. The output voltage is set by the resistor divider at the output. The Darlington pair transistor configuration provides a current gain from the input source to the LM317.



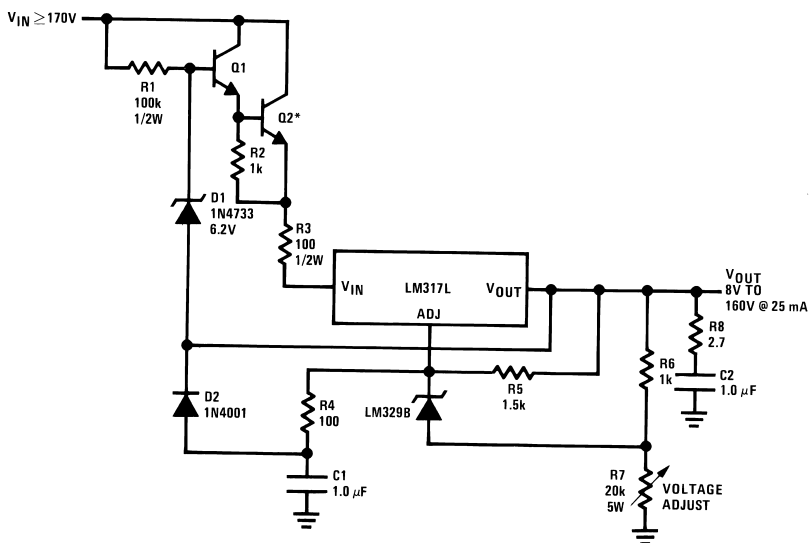
Q1, Q2: NSD134 or similar  
 C1, C2: 1 μF, 200-V mylar\*\*  
 \*Heat sink

Figure 36. Basic High-Voltage Regulator

## Typical Applications (continued)

### 8.2.21 Precision High-Voltage Regulator

This application regulates the output voltage from 8 V to 160 V at 25 mA as shown in Figure 37. The Zener diode connected from the adjust pin to  $V_{OUT}$  provides better precision than the basic high-voltage regulator.

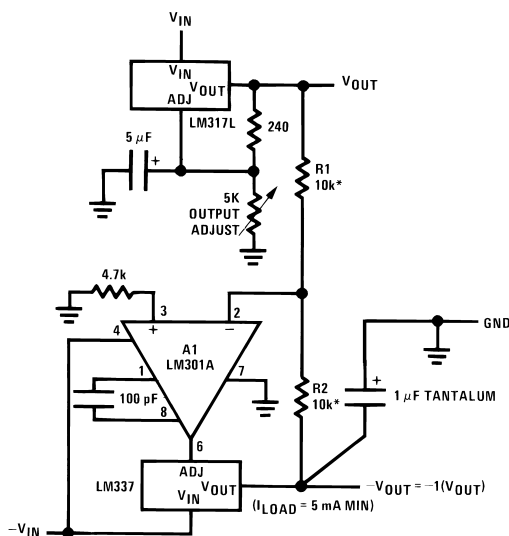


Q1, Q2: NSD134 or similar  
 C1, C2: 1  $\mu$ F, 200-V mylar\*\*  
 \*Heat sink  
 \*\*Mylar is a registered trademark of DuPont Co.

Figure 37. Precision High-Voltage Regulator

### 8.2.22 Tracking Regulator

This application regulates to an output voltage set by the output resistor divider and also uses the LM301A operational amplifier to provide a negative voltage that tracks the output voltage.



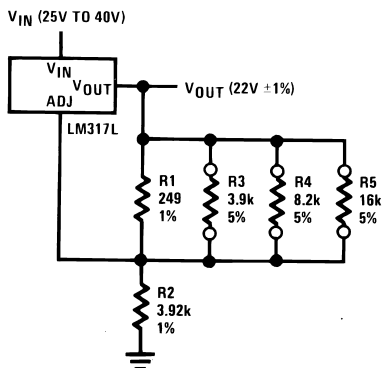
A1 = LM301A, LM307, or LF13741 only  
 R1, R2 = matched resistors with good TC tracking

Figure 38. Tracking Regulator

## Typical Applications (continued)

### 8.2.23 Regulator With Trimmable Output Voltage

This application provides an output voltage set by the output resistor divider that can be finely tuned to  $\pm 1\%$  by removing output resistors. See the trim procedure in [Figure 39](#).



#### Trim Procedure:

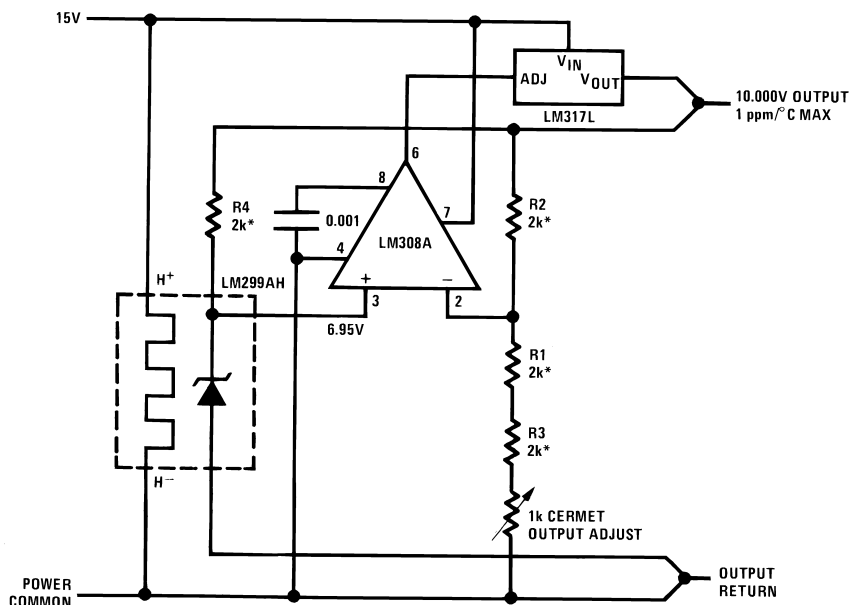
- If  $V_{OUT}$  is 23.08 V or higher, cut out R3 (if lower, don't cut it out).
- Then if  $V_{OUT}$  is 22.47 V or higher, cut out R4 (if lower, don't).
- Then if  $V_{OUT}$  is 22.16 V or higher, cut out R5 (if lower, don't).

This will trim the output to well within  $\pm 1\%$  of 22.00  $V_{DC}$ , without any of the expense or uncertainty of a trim pot (see LB-46). This technique can be used at any output voltage level.

Figure 39. Regulator With Trimmable Output Voltage

### 8.2.24 Precision Reference With Short-Circuit Proof Output

This application provides a precise output voltage with short-circuit protection. The precision results from using the LM308A operational amplifier connected between the adjust pin and output voltage pin as a comparator with the LM299AH precision reference.



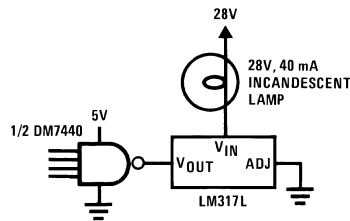
\*R1–R4 from thin-film network,  
Beckman 694-3-R2K-D or similar

Figure 40. Precision Reference With Short-Circuit Proof Output

**Typical Applications (continued)**

**8.2.25 Fully-Protected (Bulletproof) Lamp Driver**

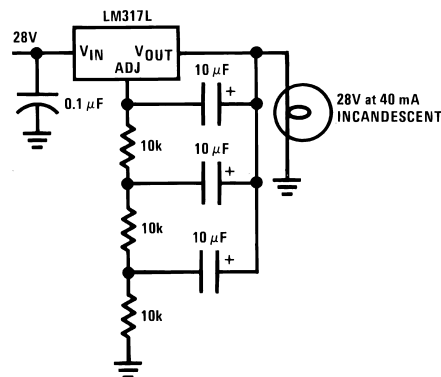
This application drives a lamp using a programmable gain instrumentation amplifier at the output.



**Figure 41. Fully-Protected (Bulletproof) Lamp Driver**

**8.2.26 Lamp Flasher**

This application uses a combination of capacitors and resistors connected between the output voltage pin and the adjust pin to cause the lamp connected at the output voltage pin to flash.



Output rate—4 flashes per second at 10% duty cycle

**Figure 42. Lamp Flasher**



## 9 Power Supply Recommendations

The input supply to the LM317L-N must be kept at a voltage level lower than the maximum input-to-output differential voltage of 40 V. When possible, the minimum dropout voltage must also be met with extra headroom to keep the LM317L-N in regulation. TI recommends using an input capacitor, especially when the input pin is located more than 6 inches away from the power supply source. For more information regarding capacitor selection, see [External Capacitors](#).

## 10 Layout

### 10.1 Layout Guidelines

Some layout guidelines should be followed to ensure proper regulation of the output voltage with minimum noise. Traces carrying the load current must be wide to reduce the amount of parasitic trace inductance and the feedback loop from  $V_{OUT}$  to ADJ should be kept as short as possible. To improve PSRR, a bypass capacitor can be placed at the ADJ pin and must be located as close as possible to the IC. In cases when  $V_{IN}$  shorts to ground, an external diode should be placed from  $V_{OUT}$  to  $V_{IN}$  to divert the surge current from the output capacitor and protect the IC. Similarly, in cases when a large bypass capacitor is placed at the ADJ pin and  $V_{OUT}$  shorts to ground, an external diode should be placed from ADJ to  $V_{OUT}$  to provide a path for the bypass capacitor to discharge. These diodes must be placed close to the corresponding IC pins to increase their effectiveness.

### 10.2 Layout Examples

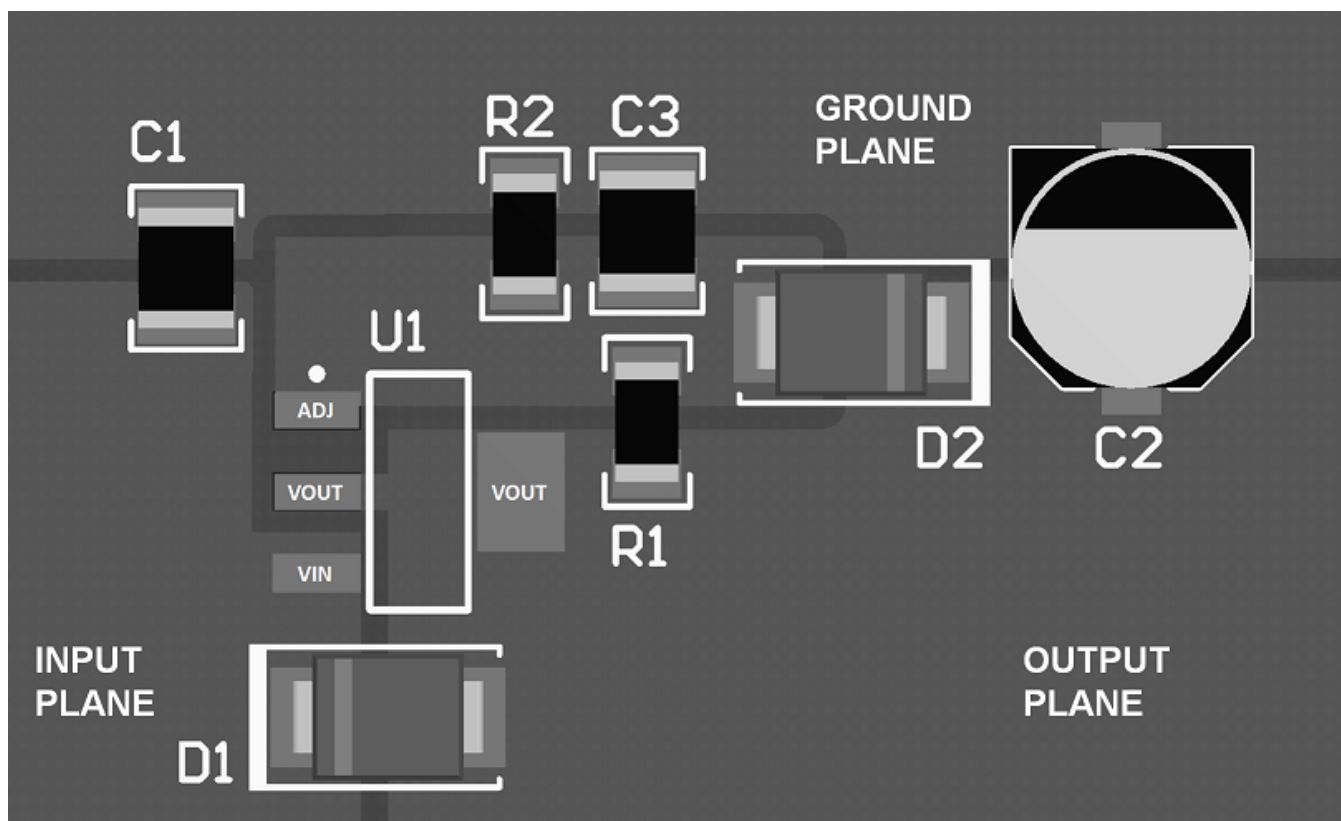
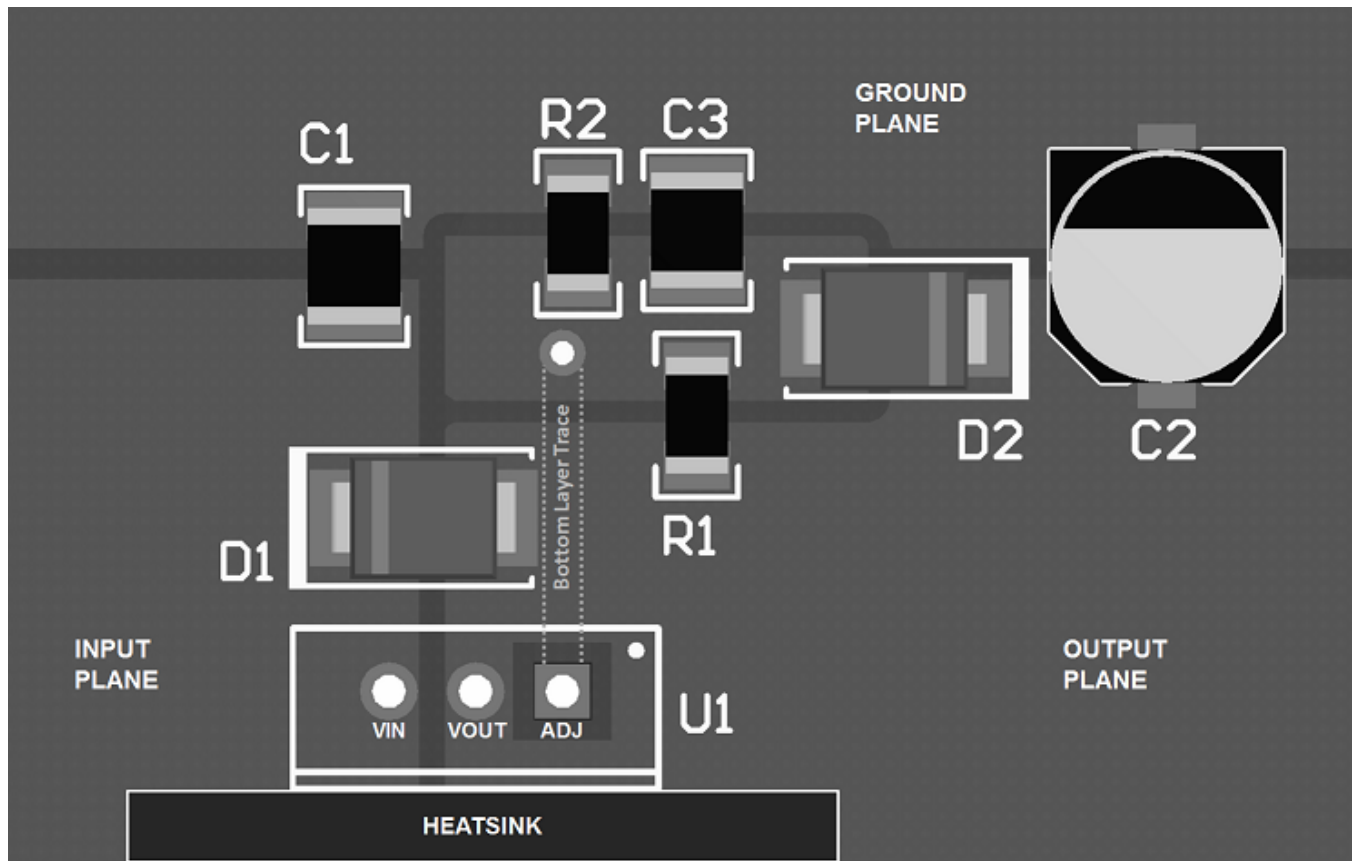


Figure 43. Layout Example (SOT-223)

**Layout Examples (continued)**

**Figure 44. Layout Example (TO-220)**
**10.3 Thermal Considerations**

When power is dissipated in an IC, a temperature gradient occurs across the IC chip affecting the individual IC circuit components. With an IC regulator, this gradient can be especially severe since power dissipation is large. Thermal regulation is the effect of these temperature gradients on output voltage (in percentage output change) per watt of power change in a specified time. Thermal regulation error is independent of electrical regulation or temperature coefficient, and occurs within 5 ms to 50 ms after a change in power dissipation. Thermal regulation depends on IC layout as well as electrical design. The thermal regulation of a voltage regulator is defined as the percentage change of  $V_{OUT}$ , per watt, within the first 10 ms after a step of power is applied. The LM317L-N specification is 0.2%/W, maximum.

In [Figure 12](#), a typical output of the LM317L-N changes only 7 mV (or 0.07% of  $V_{OUT} = -10$  V) when a 1-W pulse is applied for 10 ms. This performance is thus well inside the specification limit of  $0.2\%/W \times 1$  W = 0.2% maximum. When the 1-W pulse is ended, the thermal regulation again shows a 7-mV change as the gradients across the LM317L-N chip die out.

---

**NOTE**

The load regulation error of about 14 mV (0.14%) is additional to the thermal regulation error.

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## 11 デバイスおよびドキュメントのサポート

### 11.1 ドキュメントのサポート

#### 11.1.1 関連資料

関連資料については、以下を参照してください。

『AN-1112 DSBGA Wafer Level Chip Scale Package』(SNVA009)

### 11.2 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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**設計サポート** TIの設計サポート 役に立つE2Eフォーラムや、設計サポート・ ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。

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### 11.5 Glossary

[SLYZ022](#) — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

## 12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM317LITP/NOPB	ACTIVE	DSBGA	YPB	6	250	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 125	P 1	<a href="#">Samples</a>
LM317LITPX/NOPB	ACTIVE	DSBGA	YPB	6	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 125	P 1	<a href="#">Samples</a>
LM317LM/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	Call TI   SN	Level-1-260C-UNLIM	-40 to 125	LM317 LM	<a href="#">Samples</a>
LM317LMX/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	Call TI   SN	Level-1-260C-UNLIM	-40 to 125	LM317 LM	<a href="#">Samples</a>
LM317LZ/LFT1	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT2	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT3	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT4	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/LFT7	ACTIVE	TO-92	LP	3	2000	RoHS & Green	SN	N / A for Pkg Type		LM317 LZ	<a href="#">Samples</a>
LM317LZ/NOPB	ACTIVE	TO-92	LP	3	1800	RoHS & Green	SN	N / A for Pkg Type	-40 to 125	LM317 LZ	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM317LITP/NOPB	DSBGA	YPB	6	250	178.0	8.4	1.09	1.75	0.66	4.0	8.0	Q1
LM317LITPX/NOPB	DSBGA	YPB	6	3000	178.0	8.4	1.09	1.75	0.66	4.0	8.0	Q1
LM317LMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM317LITP/NOPB	DSBGA	YPB	6	250	208.0	191.0	35.0
LM317LITPX/NOPB	DSBGA	YPB	6	3000	208.0	191.0	35.0
LM317LMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
LM317LM/NOPB	D	SOIC	8	95	495	8	4064	3.05



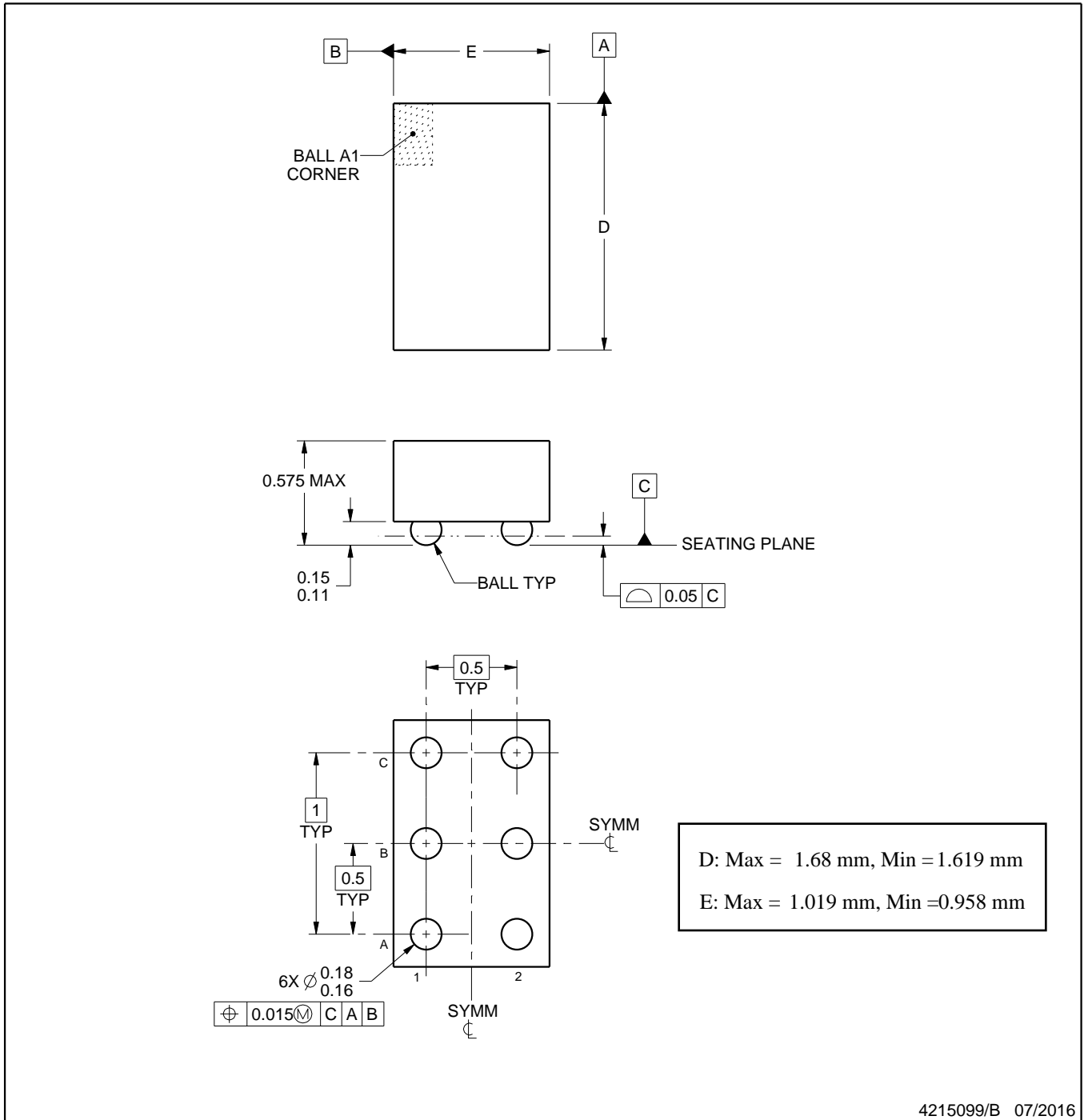
YPB0006



# PACKAGE OUTLINE

DSBGA - 0.575 mm max height

DIE SIZE BALL GRID ARRAY



4215099/B 07/2016

NOTES:

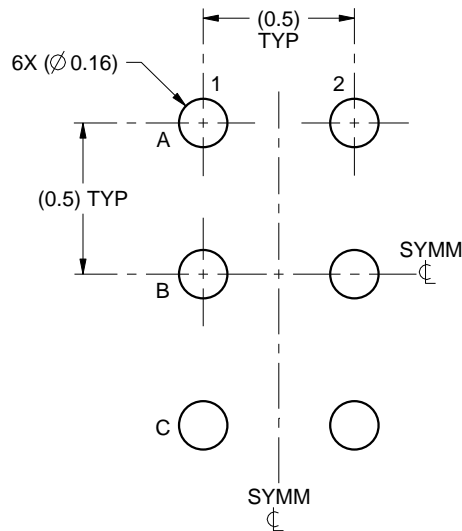
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

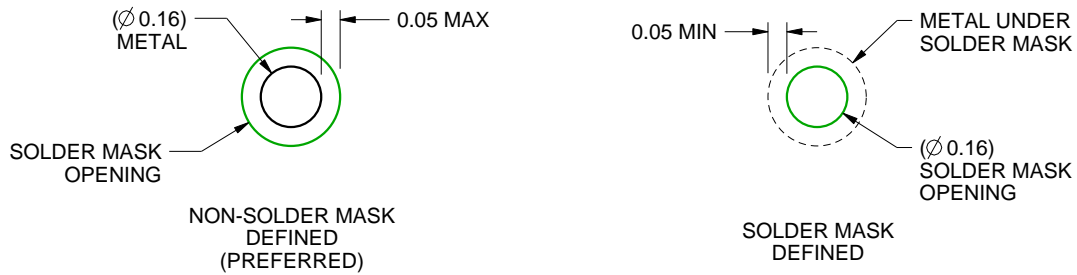
YPB0006

DSBGA - 0.575 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:40X



SOLDER MASK DETAILS  
NOT TO SCALE

4215099/B 07/2016

NOTES: (continued)

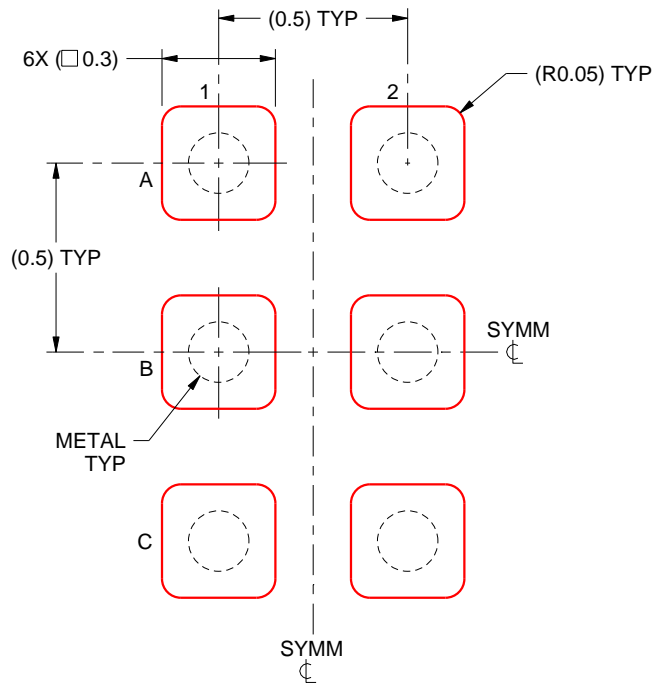
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YPB0006

DSBGA - 0.575 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.125mm THICK STENCIL  
SCALE:50X

4215099/B 07/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



D0008A

# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed  $.006$  [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

# EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
 EXPOSED METAL SHOWN  
 SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

LP 3

TO-92 - 5.34 mm max height

TRANSISTOR OUTLINE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040001-2/F

LP0003A



PACKAGE OUTLINE

TO-92 - 5.34 mm max height

TO-92



FORMED LEAD OPTION  
OTHER DIMENSIONS IDENTICAL  
TO STRAIGHT LEAD OPTION

STRAIGHT LEAD OPTION

4215214/B 04/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
  - a. Straight lead option available in bulk pack only.
  - b. Formed lead option available in tape and reel or ammo pack.
  - c. Specific products can be offered in limited combinations of shipping medium and lead options.
  - d. Consult product folder for more information on available options.

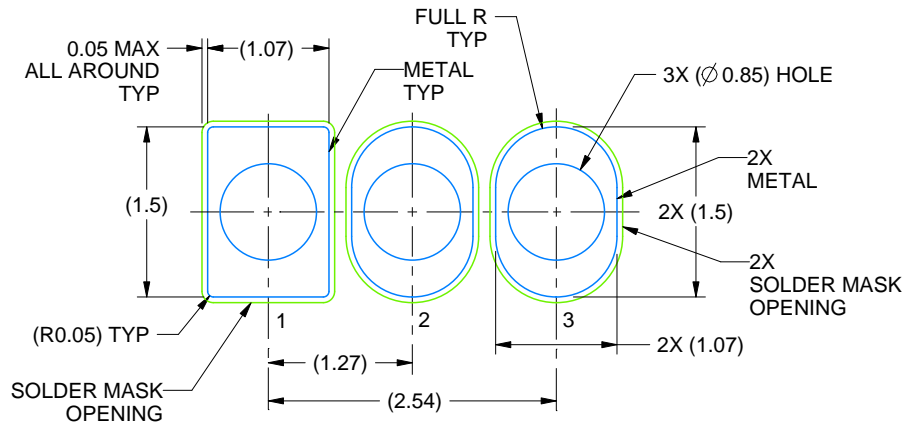


# EXAMPLE BOARD LAYOUT

LP0003A

TO-92 - 5.34 mm max height

TO-92



LAND PATTERN EXAMPLE  
STRAIGHT LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X



LAND PATTERN EXAMPLE  
FORMED LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X

4215214/B 04/2017

# TAPE SPECIFICATIONS

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/B 04/2017

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